SLLS044D - NOVEMBER 1988 - REVISED DECEMBER 1999

8 | V_{CC}

5 GND

7 | B

6 🛮 A

D OR P PACKAGE (TOP VIEW)

RE

DE [3

D

- **Bidirectional Transceiver**
- Meets or Exceeds the Requirements of TIA/EIA-422-B, TIA/EIA-485-A, and ITU **Recommendation V.11**
- **High-Speed Advanced Low-Power Schottky** Circuitry
- Low Skew . . . 6 ns Max
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- Low Supply-Current Requirements . . . 30 mA Max
- Wide Positive and Negative Input/Output **Bus-Voltage Ranges**
- Driver Output Capacity . . . ±60 mA
- Thermal-Shutdown Protection
- **Driver Positive and Negative Current** Limiting
- Receiver Input Impedances . . . 12 k Ω Min
- Receiver Input Sensitivity . . . ±200 mV Max
- Receiver Input Hysteresis . . . 120 mV Typ
- Fail Safe . . . High Receiver Output With Inputs Open
- **Operates From a Single 5-V Supply**
- Glitch-Free Power-Up and Power-Down **Protection**
- Interchangeable With National DS3695 and **DS3695A**

description

The TL3695 differential bus transceiver is designed for bidirectional data communication on multipoint bus-transmission lines. It is designed for balanced transmission lines and meets TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11.

The TL3695 combines a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can be externally connected together to function as a directional control. The driver differential outputs and the receiver differential inputs are connected internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus when the driver is disabled or $V_{
m CC}$ = 0. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party line applications.

The TL3695 is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



AVAILABLE OPTIONS

	PACKAGED DEVICES			
TA	SMALL OUTLINE	PLASTIC DIP		
	(D)	(P)		
0°C to 70°C	TL3695D	TL3695P		

The D package is available taped and reeled. Add the suffix R to device type (e.g., TL3695DR).

Function Tables

DRIVER

INPUT	ENABLE	OUTPUTS		
D	DE	Α	В	
Н	Н	Н	L	
L	Н	L	Н	
X	L	Z	Z	

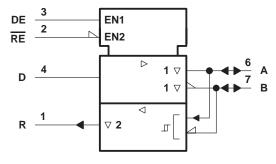
H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

RECEIVER

DIFFERENTIAL INPUTS A – B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
$-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
X	Н	Z
Inputs open	L	Н

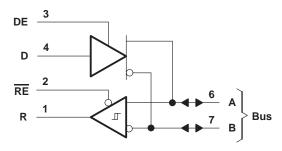
H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

logic symbol†

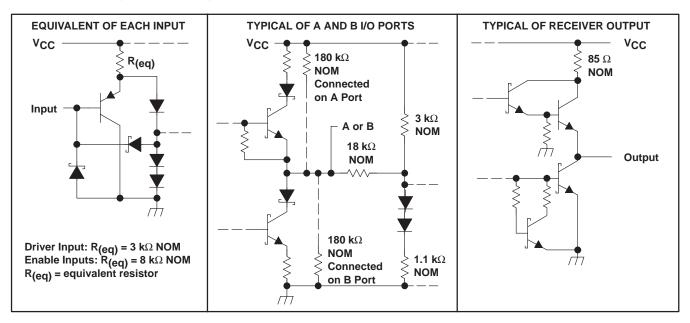


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	7 V
Voltage range at any bus terminal	
Enable input voltage, V _I	5.5 V
Operating free-air temperature range, T _A	0°C to 70°C
Package thermal impedance, θ_{JA} (see Note 2): D package	97°C/W
PW package	85°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{Stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

TL3695 DIFFERENTIAL BUS TRANSCEIVER

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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
Valta and a surface to a serior of the angular form of the serior of the				12	V
Voltage at any bus terminal (separately or common mode), V _I or V _{IC}				-7	V
High-level Input voltage, VIH	D, DE, and RE	2			V
Low-level Input voltage, V _{IL}	D, DE, and RE			0.8	V
Differential input voltage, V _{ID} (see Note 3)				±12	V
High level output ourrent leve	Driver			- 60	mA
High-level output current, IOH	Receiver			- 400	μΑ
Low level output output lev	Driver			60	A
Low-level output current, IOL	Receiver			8	mA
Operating free-air temperature, TA		0		70	°C

NOTE 3: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONI	TEST CONDITIONS†		TYP‡	MAX	UNIT
VIK	Input clamp voltage	I _I = -18 mA				-1.5	V
٧o	Output voltage	I _O = 0		0		6	V
V _{OD1}	Differential output voltage	IO = 0		1.5		5	V
IVOD2I	Differential output voltage	R _L = 100 Ω,	See Figure 1	1/2 V _{OD1} or 2§			V
		$R_L = 54 \Omega$,	See Figure 1	1.5	2.5	5	V
V _{OD3}	Differential output voltage	$V_{test} = -7 \text{ V to } 12 \text{ V},$	See Figure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage¶					±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega$,	See Figure 1			3	V
∆ Voc	Change in magnitude of common-mode output voltage¶					±0.2	V
la.	Output current	Output disabled,	V _O = 12 V			1	mA
Ю		See Note 4	$V_O = -7 V$			-0.8	mA
lн	High-level input current	V _I = 2.4 V				20	μΑ
I _{IL}	Low-level input current	V _I = 0.4 V				-200	μΑ
		V _O = -6 V				-250	
	Short-circuit output current#	VO = 0				-150	mA
los	Short-circuit output current"	VO = VCC				250	IIIA
		VO = 8 V				250	
laa	Cumply current	No load	Outputs enabled		23	50	mA
Icc	Supply current	INU IUdu	Outputs disabled		19	35	IIIA

[†] The power-off measurement in TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

	PARAMETER	TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
t _d (OD)	Differential-output delay time					8	22	ns
	Skew ($ t_{d(ODH)} - t_{d(ODL)} $)	$C_{L1} = C_{L2} = 100 \text{ pF},$	$R_L = 60 \Omega$,	See Figure 3		1	8	ns
t _t (OD)	Differential output transition time					8	18	ns
^t PZH	Output enable time to high level	$C_L = 100 pF$,	$R_L = 500 \Omega$,	See Figure 4			50	ns
tPZL	Output enable time to low level	C _L = 100 pF,	$R_L = 500 \Omega$,	See Figure 5			50	ns
tPHZ	Output disable time from high level	C _L = 15 pF,	$R_L = 500 \Omega$,	See Figure 4		8	30	ns
tPLZ	Output disable time from low level	C _L = 15 pF,	$R_L = 500 \Omega$,	See Figure 5		8	30	ns

 $[\]pm$ All typical values are at V_{CC} = 5 V and T_A = 25°C.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

[§] The minimum V_{OD2} with a $100-\Omega$ load is either 1/2 V_{OD1} or 2 V, whichever is greater. $\P\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

[#] Duration of the short circuit should not exceed one second for this test.

NOTE 4: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
Vo	V_{oa}, V_{ob}	V _{oa} , V _{ob}
V _{OD1}	Vo	V _O
V _{OD2}	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
IVOD3I		V _t (test termination measurement 2)
V _{test}		V _{tst}
Δ V _{OD}	$ \vee_t - \overline{\vee}_t $	$ V_t - \overline{V}_t $
Voc	V _{os}	V _{os}
Δ VOC	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	I _{sa} , I _{sb}	
IO	I _{xa} , I _{xb}	I _{ia} , I _{ib}

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$			0.2	V
V _{IT} _	Negative-going input threshold voltage	V _O = 0.5 V,	I _O = 8 mA	-0.2‡			V
V _{hys}	Hysteresis voltage (V _{IT+} -V _{IT-})	$V_{OC} = 0$			70		mV
VIK	Enable-input clamp voltage	I _I = -18 mA				-1.5	V
VOH	High-level output voltage	V_{ID} = 200 mV or input I_{OH} = -400 μ A,	ts open, See Figure 6	2.4			٧
V	Low lovel output voltage	$V_{ID} = -200 \text{ mV},$	I _{OL} = 16 mA			0.5	V
VOL	Low-level output voltage	See Figure 6	I _{OL} = 8 mA			0.45	V
loz	High-impedance-state output current	V _O = 0.4 V to 2.4 V				±20	μΑ
1.	Line input surrent	Other input = 0,	nput = 0, V _I = 12 V		1		
l II	Line input current	See Note 5	V _I = -7 V			-0.8	mA
lн	High-level enable-input current	V _{IH} = 2.7 V				20	μΑ
IIL	Low-level enable-input current	V _{IL} = 0.4 V				-100	μΑ
rı	Input resistance			12			kΩ
los	Short-circuit output current§	V _O = 0		-15		-85	mA
loo	Supply current	No load	Outputs enabled		23	50	m A
Icc		INO IOAU	Outputs disabled		19	35	mA

NOTE 5: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions.



[†] All typical values are at V_{CC} = 5 V and T_A = 25°C. ‡ The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

[§] Duration of the short circuit should not exceed one second for this test.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, C_L = 15 pF

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$		14	37	ns
tPHL	Propagation delay time, high- to low-level output	See Figure 7		14	37	ns
^t PZH	Output enable time to high level	See Figure 8		7	20	ns
tPZL	Output enable time to low level	See Figure 6		7	20	ns
^t PHZ	Output disable time from high level	See Figure 8		7	16	ns
tPLZ	Output disable time from low level	See Figure 6		8	16	ns

 $[\]dagger$ All typical values are at V_{CC} = 5 V and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

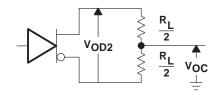


Figure 1. Driver V_{OD} and V_{OC}

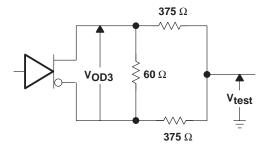
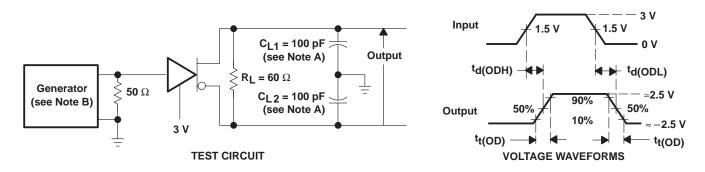


Figure 2. Driver V_{OD3}



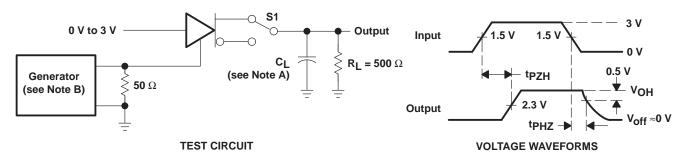
NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{f} \leq$ 6 ns, $t_{O} = 50 \Omega$.

Figure 3. Driver Differential-Output Test Circuit and Voltage Waveforms



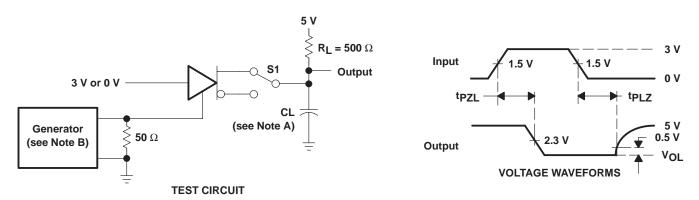
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{\Gamma} \leq$

Figure 4. Driver Test Circuit and Voltage Waveforms



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{\Gamma} \leq$

Figure 5. Driver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION

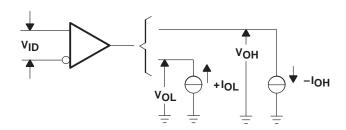
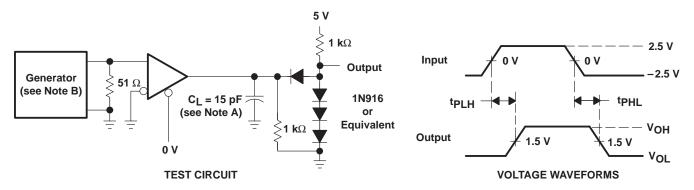


Figure 6. Receiver V_{OH} and V_{OL}

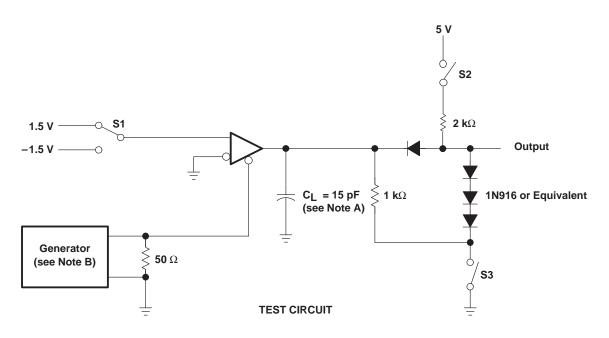


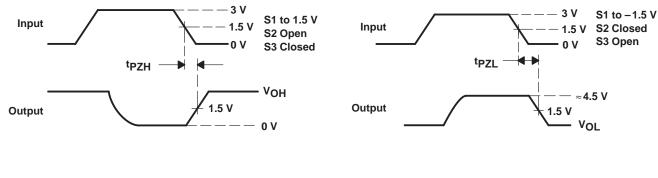
NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{\Gamma} \leq$

Figure 7. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION





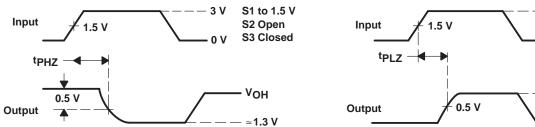
S1 to -1.5 V

S2 Closed

S3 Open

≈ 1.3 V

 v_{OL}



VOLTAGE WAVEFORMS

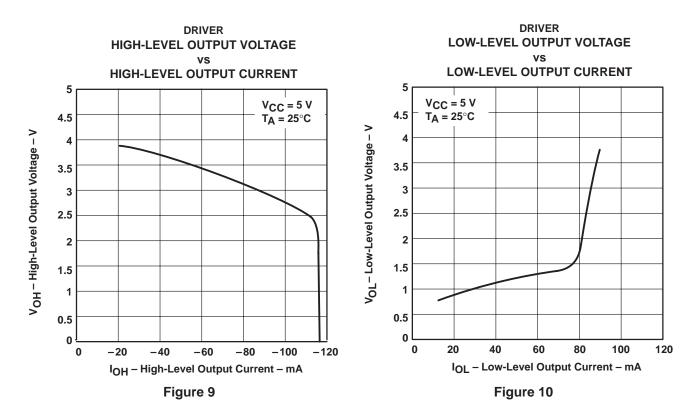
NOTES: A. C_L includes probe and jig capacitance.

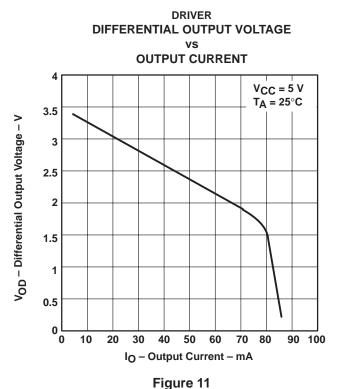
B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 10 ns, $t_f \leq$ 10 ns, $Z_Q =$ 50 Ω .

Figure 8. Receiver Test Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS[†]





† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

TYPICAL CHARACTERISTICS[†]

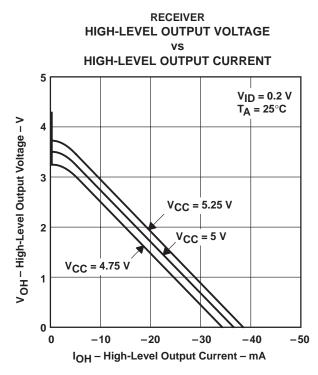
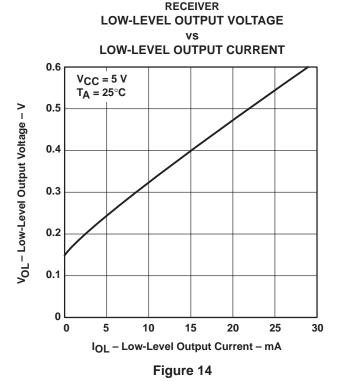


Figure 12



RECEIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

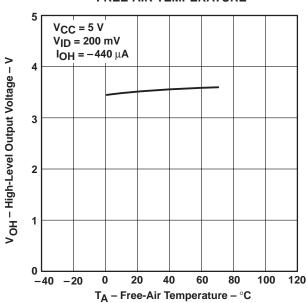


Figure 13

RECEIVER LOW-LEVEL OUTPUT VOLTAGE vs

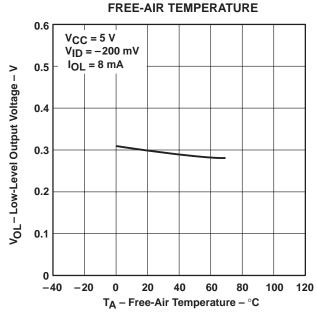
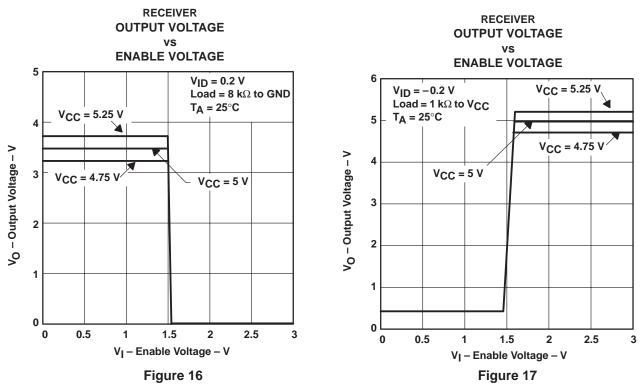


Figure 15

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

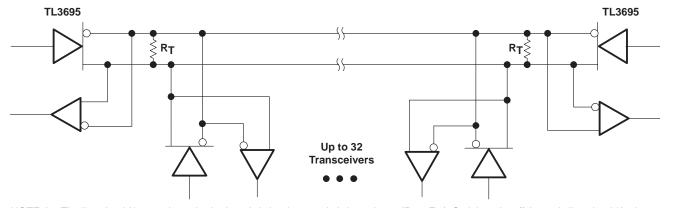


TYPICAL CHARACTERISTICS[†]



† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible.

Figure 18. Typical Application Circuit



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL3695D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3695DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3695DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3695DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3695DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3695DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3695P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL3695PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

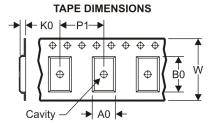
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TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

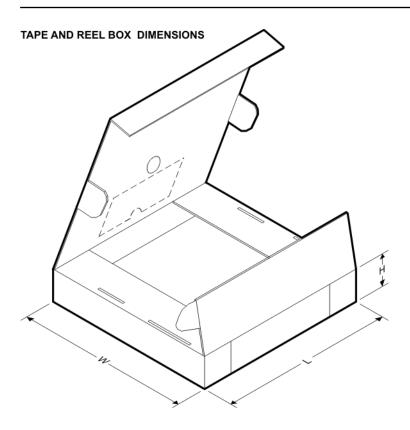
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3695DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3695DR	SOIC	D	8	2500	340.5	338.1	20.6

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

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